

ABSTRACT

The picking of a semiconductor chip from a foil takes place by means of a chip gripper which bears on a bondhead and can be deflected in a predetermined direction and with the aid of a needle. An inductive sensor serves the precise measurement of the deflection of the chip gripper with reference to the bondhead. The pick process itself is characterised by the following steps:

- a) Lowering the chip gripper to a height z_0 , that is greater than an average height of the surface of the semiconductor chips so that the chip gripper does not yet touch the semiconductor chip,
- b) Raising the needle to a predetermined height z_1 , whereby the needle raises the semiconductor chip in order to bring the semiconductor chip into contact with the chip gripper and then to increase the height of the chip gripper, and
- c) Raising the chip gripper, whereby the semiconductor chip detaches itself from the needle.